

IN THE CLAIMS

1. (canceled)
2. (canceled)
3. (canceled)
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16. (canceled)
17. (canceled)

18. (original) A connection component for a semiconductor assembly, said component comprising:

A. a support structure having a dielectric layer and a top surface;

B. a copper layer disposed over the top surface, said copper layer having a plurality of first regions and a second region;

C. a plurality of graphite regions disposed over the plurality of first regions, each of said plurality of graphite regions associated with one of said plurality of first regions and prepared by depositing graphite over the associated first regions; and

D. a plurality of leads disposed over the copper layer, each said lead having a terminal end permanently attached to said second region; and a tip end offset from the terminal

end, associated with one of said plurality of graphite regions,
and releasably connected to the associated graphite region.

19. (canceled)

20. (canceled)